

the dielectric layer surface; laminating multiple capacitor elements and bonding adjacent conductor electrodes with conductive adhesive; bonding adjacent surface-roughened conductor electrodes to achieve electrical contact; and providing the terminal electrode. This enables to increase dielectric constant of the dielectric layer compared to the dielectric layer formed only of the organic polymer film, realizing the manufacture of a small laminated capacitor with large capacitance made by laminating multiple capacitor elements without damaging the dielectric layer.

In the step of forming the compound dielectric layer consisting of the organic polymer film and the oxide film of the conductor, both electro-deposition method and anodization method are employed. This enables to form the compound dielectric layer with good insulation performance by covering the surface-roughened conductor layer uniformly.

IN THE CLAIMS:

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Please cancel claims 1-36.

Please amend claims 41-43 as follows:

41. (Amended) A method of manufacturing laminated capacitors, said method comprising the steps of:

forming one of:

dielectrics made of organic polymer, and composite dielectrics made of organic polymer and oxide of a metal constituting said conductor;

forming an insulating layer at least on said conductor;

forming an opposite electrode on said dielectrics to complete a capacitor element;

laminating a plurality of said capacitor elements; and

forming an external connection terminal.

42. (Amended) The method of manufacturing the laminated capacitors as defined in Claim 41, wherein said dielectrics is formed by electro-depositing organic polymer.

43. (Amended) The method of manufacturing laminated capacitors as defined in Claim 41, wherein said compound dielectrics is formed by simultaneous progression of:

electrodeposition of organic polymer; and

anodization of a metal constituting said conductor.

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